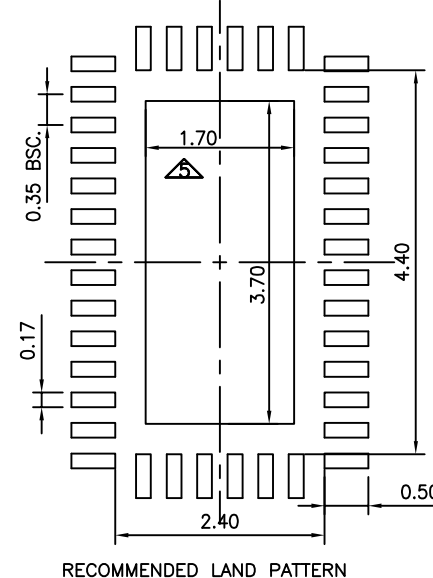
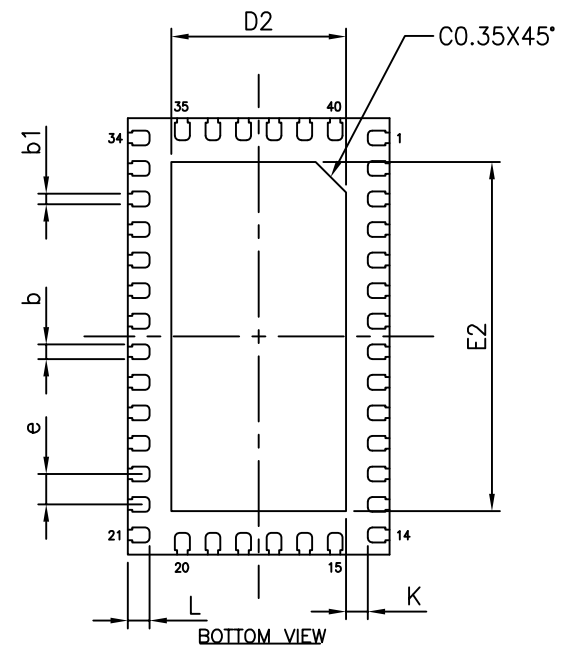
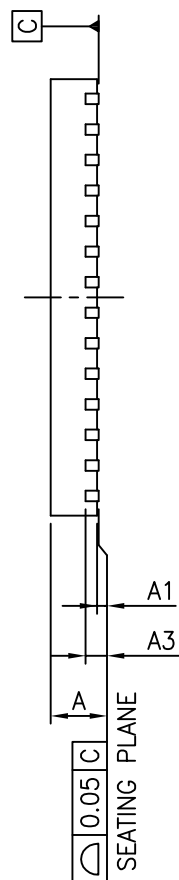


SYMBOLS	MIN.	NOM.	MAX.
A	0.50	0.55	0.60
A1	0.00	0.02	0.05
A3	0.150 REF.		
b	0.12	0.17	0.22
b1	0.07	0.12	0.17
D	2.90	3.00	3.10
E	4.90	5.00	5.10
e	0.35 BSC		
L	0.20	0.25	0.30
K	0.20	—	—
D2	1.95	2.00	2.05
E2	3.95	4.00	4.05



NOTE :

1. ALL DIMENSIONS ARE IN mm. ANGLES IN DEGREES.
2. COPLANARITY APPLIES TO THE EXPOSED THERMAL PAD AS WELL AS THE TERMINALS.
3. REFER JEDEC MO-228
4. RECOMMENDED LAND PATTERN IS FOR REFERENCE ONLY.
5. THERMAL PAD SOLDERING AREA (MESH STENCIL DESIGN IS RECOMMENDED).

**DIODES**  
INCORPORATED

**PERICOM** A PRODUCT LINE OF DIODES INCORPORATED  
ENABLING SERIAL CONNECTIVITY

DATE: 10/13/17

DESCRIPTION: 40-Contact, Ultra Thin Quad Flat No-Lead (UQFN)

PACKAGE CODE: ZTFA (ZTFA40)

DOCUMENT CONTROL #: PD-2231

REVISION: --